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4.1 Handling Precautions	





1.4 Package Dimension

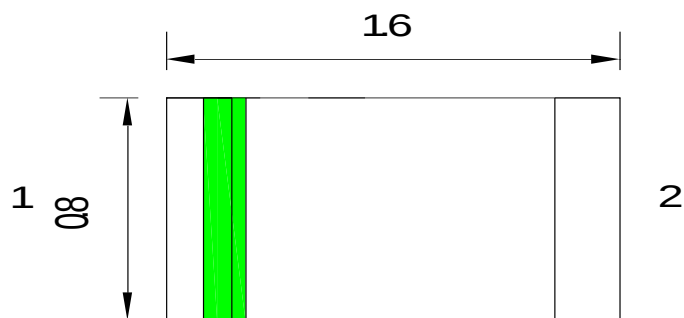


Fig.1-1 Top view

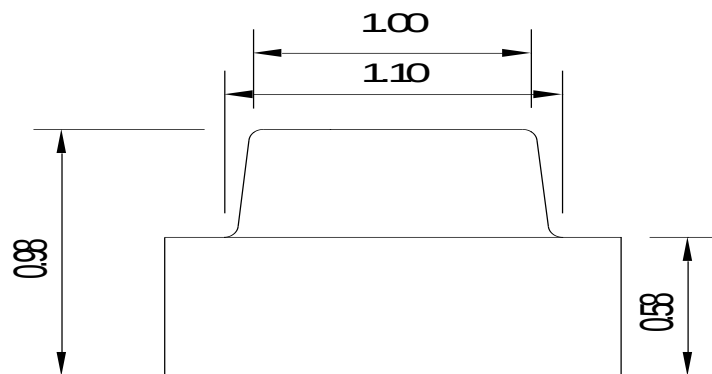


Fig.1-2 Side view

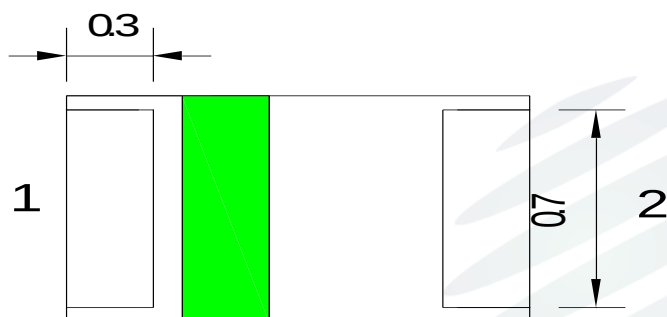


Fig.1-3 Bottom view

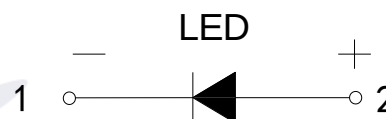


Fig.1-4 Polarity

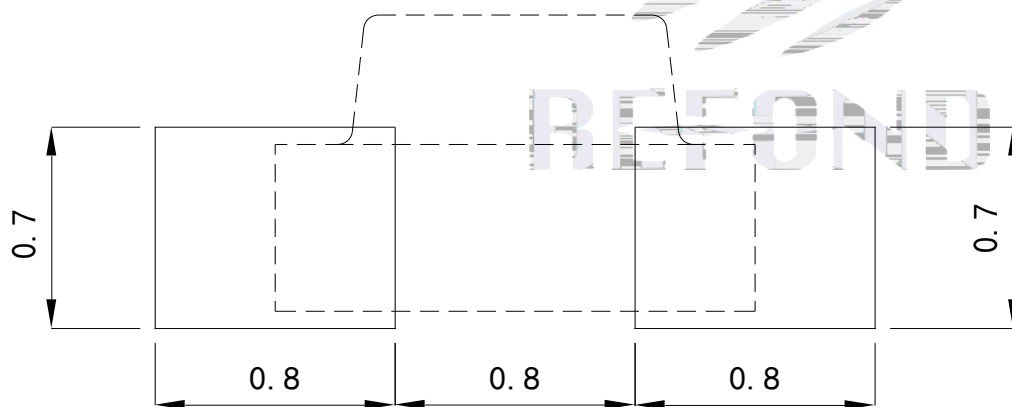


Fig.1-5 Soldering patterns

Notes

1. All dimensions units are millimeters.

All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.



1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Test Condition	Symbol		Value			Unit
				Min. ()	Typ.	Max.	
Spectral Half Bandwidth	$I_F=20\text{mA}$	Δ		--	15	--	nm
Forward Voltage	$I_F=20\text{mA}$	V_F	F2	2.7	--	2.8	V
			G1	2.8	--	2.9	V
			G2	2.9	--	3.0	V
			H1	3.0	--	3.1	V
			H2	3.1	--	3.2	V
			I1	3.2	--	3.3	V
			I2	3.3	--	3.4	V
Dominant Wavelength	$I_F=20\text{mA}$	λ_D	J1	3.4	--	3.5	V
			C00	460	--	465	nm
			D00	465	--	470	nm
			E00	470	--	475	nm
Luminous Intensity	$I_F=20\text{mA}$	I_v	F00	475	--	480	nm
			E00	43	--	65	mcd
			F00	65	--	100	mcd
			G00	100	--	150	mcd
Viewing Angle	$I_F=20\text{mA}$	2θ	H00	150	--	230	mcd
				--	140	--	deg
Reverse Current	$V_R=5\text{V}$	I_R		--	--	10	μA
Thermal Resistance.	$I_F=20\text{mA}$	R_{THJ-S}		--	--	450	$^{\circ}\text{W}$

Notes : $V_R=5\text{V}$ For test conditions. $V_R=5\text{V}$



Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	P_d	105	mW
Forward Current	I_F	30	mA
Peak Forward Current Of Pulse	I_{FP}	60	mA
Electrostatic Discharge (HBM)	E_{SD}	1000	V
Operating Temperature	T_{opr}	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +100	°C
Junction Temperature	T_j	105	°C

Notes

1. 1/10 Duty cycle, 0.1ms pulse width. 0.1ms, 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. $\pm 0.1V$.
3. The above dominant wavelength measurement allowance tolerance is $\pm 2nm$. $\pm 2nm$.
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$. $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED



1.6 Typical Optical Characteristics Curves

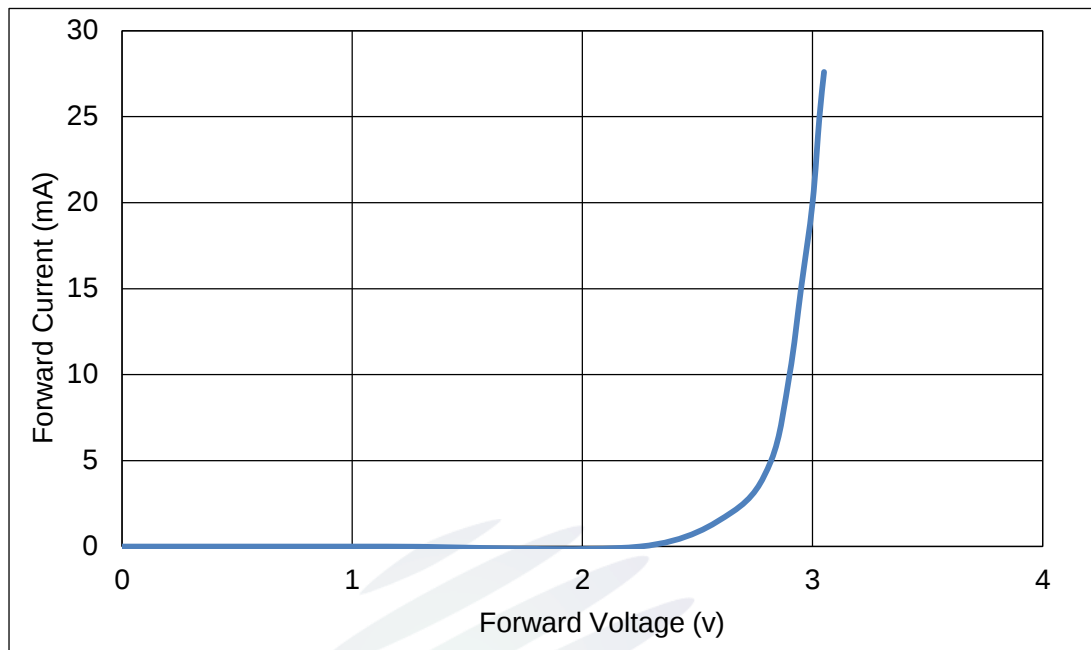


Fig 1-6 Forward Voltage Vs Forward Current

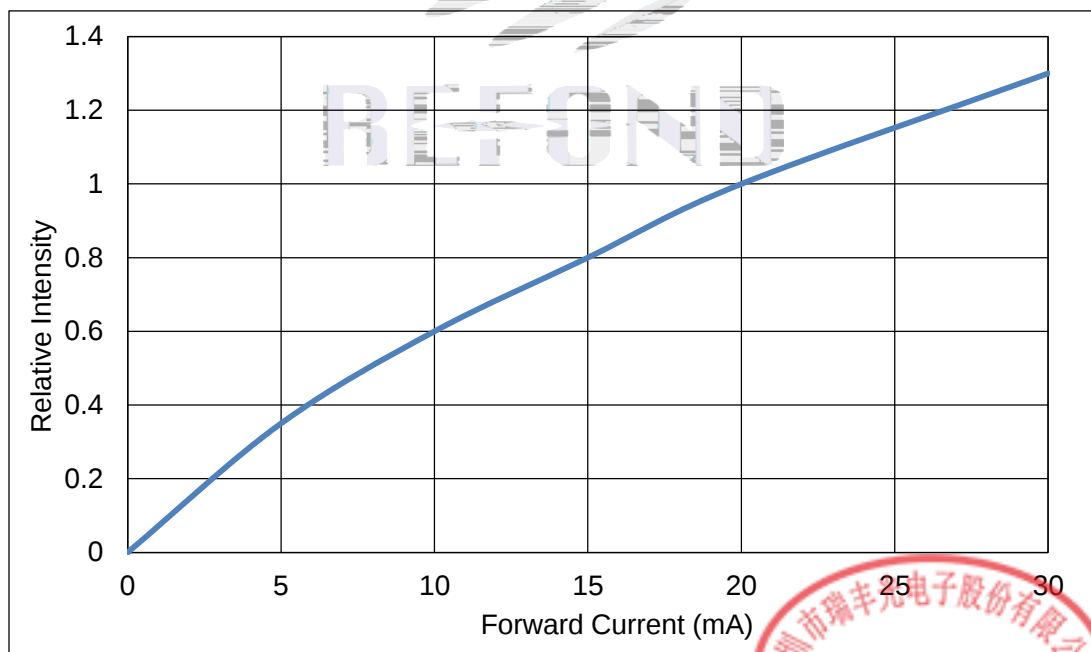


Fig 1-7 Forward Current Vs Relative Intensity



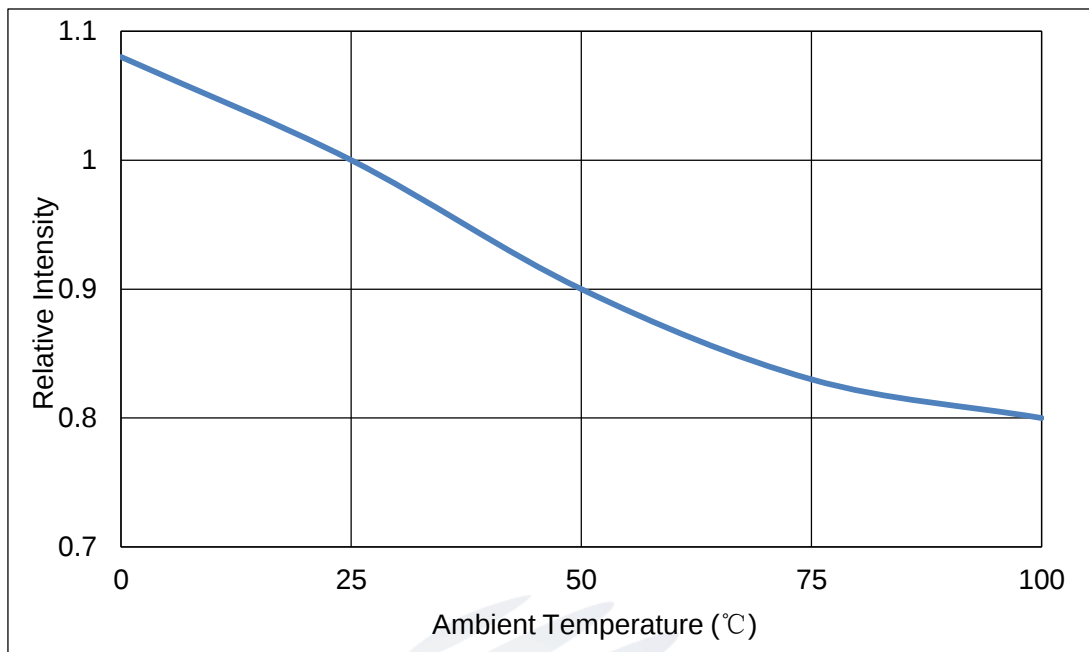


Fig 1-8 Pin Temperature Vs Relative Intensity

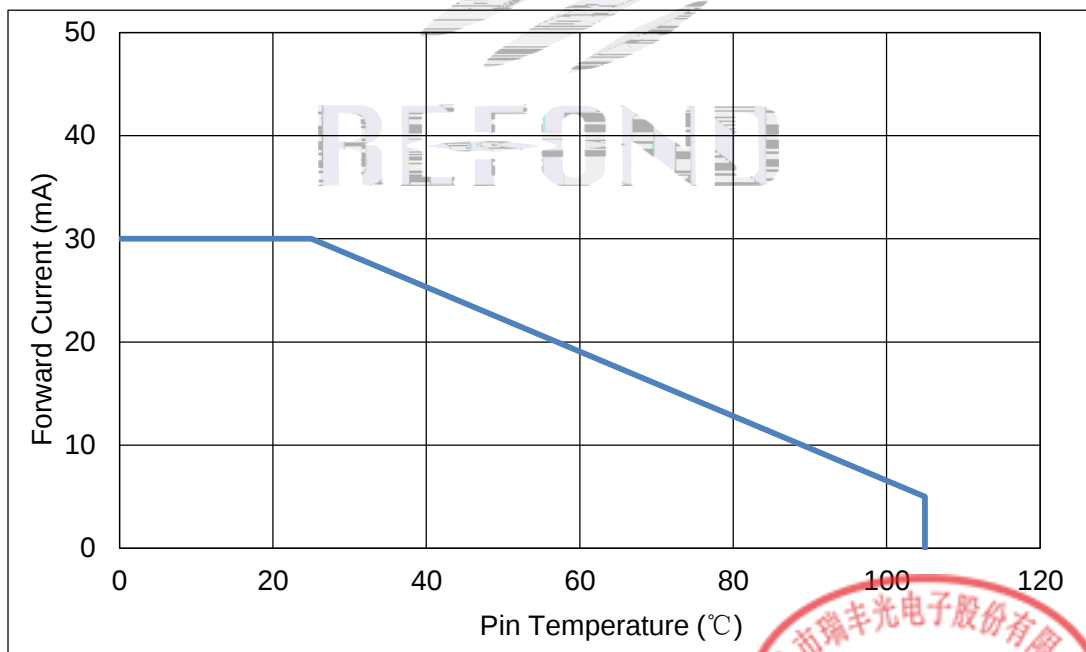
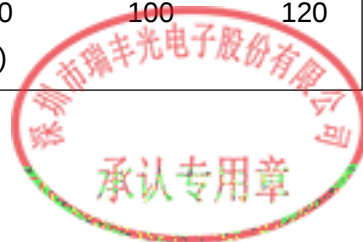


Fig 1-9 Pin Temperature Vs Forward Current



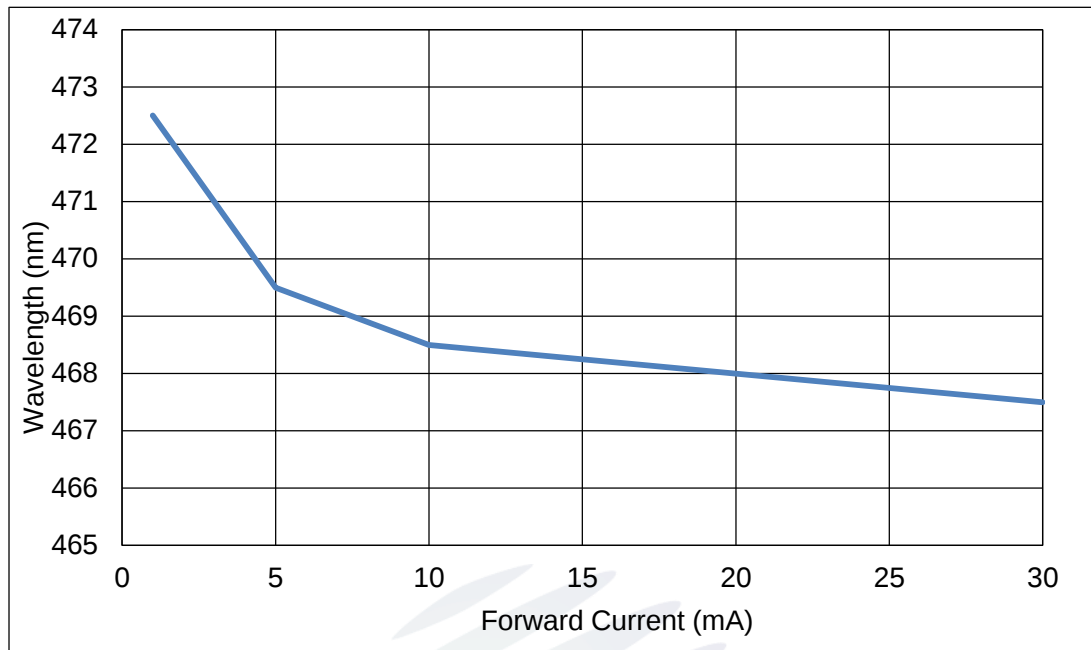


Fig 1-10 Forward Current Vs Dominate Wavelength (Ta=25°C)

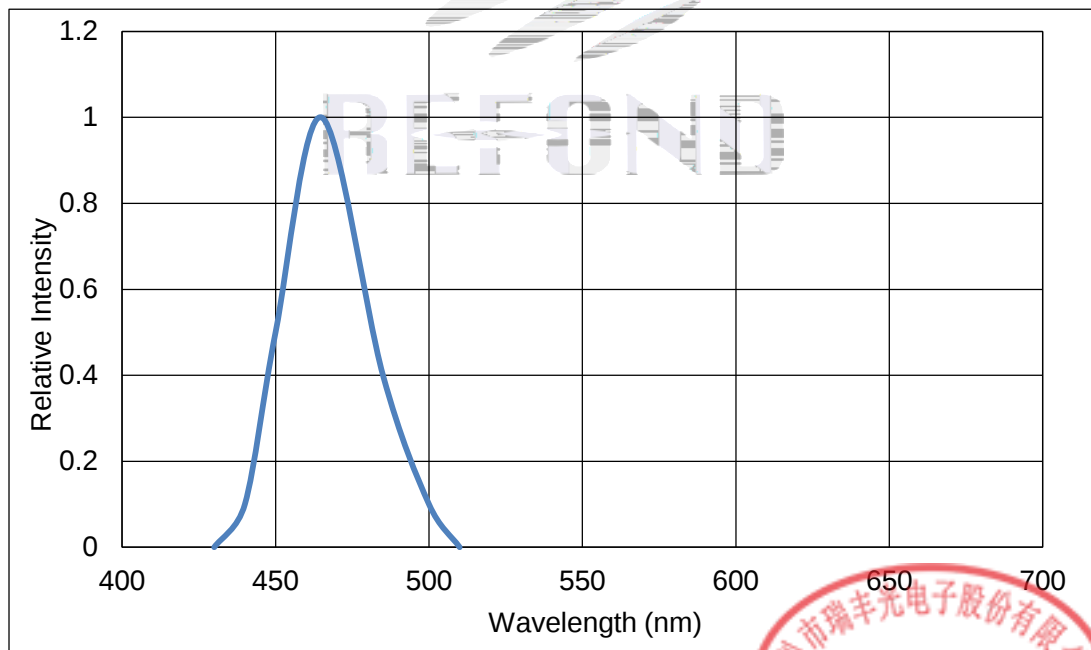
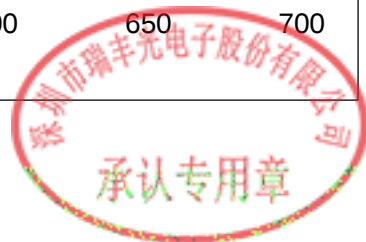


Fig 1-11 Relative Intensity Vs Wavelength (Ta=25°C)



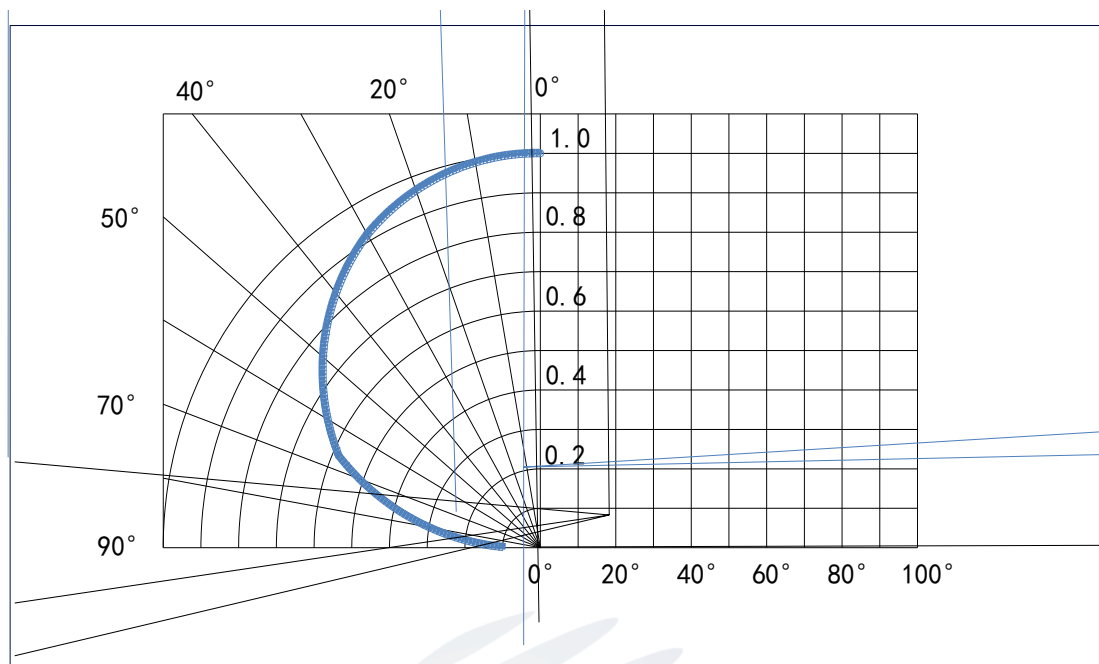


Fig 1-12 Diagram characteristics of radiation

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2. Packaging

2.1 Packaging Specification

Package:4000pcs/reel. 4000pcs

2.1.1 Carrier Tape Dimension

Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

Table 2-1 Dimension

A	8.0±0.1mm
B	178±1mm
C	60±1mm
D	13.0±0.5mm

Fig.2-2 Reel Dimension

Notes

The tolerances unless mentioned $\pm 0.1\text{mm}$. Unit : mm ± 0.1

2.1.3 Label Form Specification

PART NO:		
SPEC NO:		
LOT	NO	
		
QTY:		
DATE:		

Fig. 2-3 Label Form Specification

Table 2-2 Parameter

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V _F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

2.2 Moisture Resistant Packing



Fig.2-4 Moisture Resistant Packing



2.3 Cardboard Box

Fig.2-5



2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	$I_F=20\text{mA}$	-	$U.S.L^*) \times 1.1$
Reverse Current	I_R	$V_R=5\text{V}$	-	$U.S.L^*) \times 2.0$
Luminous Flux		$I_F=20\text{mA}$	$L.S.L^*) \times 0.7$	-

Notes

1.U.S.L: Upper standard level

L.S.L: Lower standard level

2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. When customers applies the LED to the series and parallel circuit,should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.

LED

3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.



3. SMT Reflow Soldering Instructions SMT 回流焊说明

3.1 SMT Reflow Soldering Instructions SMT

Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Parameter

Average temperature rise speed	Tsmax TP	3 °C/ Max 3 °C/ s
Preheating: minimum temperature	(Tsmín)	150 °C
Preheating: Max temperature	(Tsmax)	200 °C
Preheating: Time	Tsmin Tsmax	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature	(TL)	217 °C

Time limited to maintain high temperature: The Time (tL)

Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged.

24 LED

(2)Whensoldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

(1) When do soldering by hand, keep the temperature of iron below less 300℃ less than 3 seconds.

300

3

(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED

LED

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3.1.3 Cautions

(1) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED PCB

(2) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.



4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED LED 100PPM.

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. LED LED

900PPM 900PPM
1500PPM.

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse effect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. LED

LED

LED

LED



(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

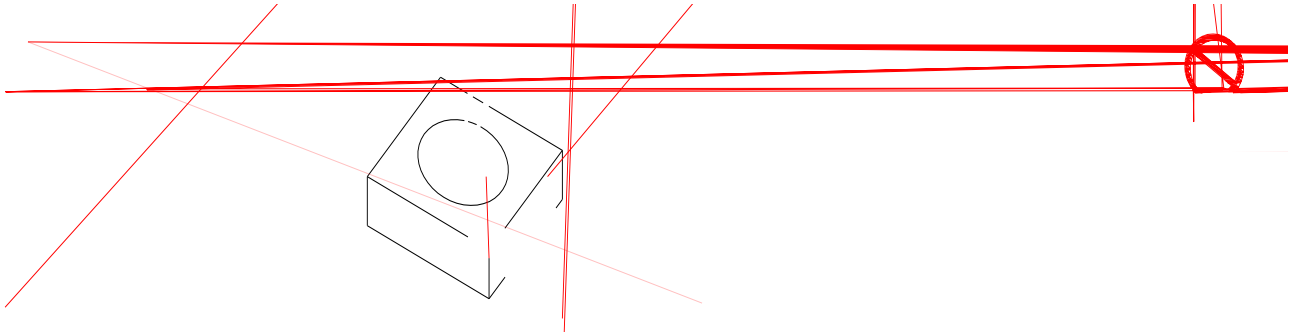


Fig 4-1

产品使用注意事项

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the

LED.

LED

Table 4-1Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	≤ 30	$\leq 75\%$	Within 1 Year From Date
	After Opening Aluminum Bag	≤ 30	$\leq 60\%$	168hours 168
Baking		60 ± 5	-	≥ 24 hours 24

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Declare

This specification is written both in English and in Chinese and the latter is formal.